

Patent and Trademark Office

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APPLICATION NO. FILING DATE		FIRST NAMED INVENTOR			ATTORNEY DOCKET NO.	
09/100,838	06/19/98	MURARI		В	851063.425	
		MM(***) / 0 77 1 (<u>,</u> ¬	EXAMINER		
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Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

PTO-90C (Rev. 2/95)

U.S. G.P.O. 2000 ; 465-188/25268

1- File Copy

Office Action Summary

Application No. 09/100,838

Applicant(s)

Murari et al.

Examiner

H. Kwok

Group Art Unit 2856



Responsive to communication(s) filed on May 1, 2000	·
☐ This action is FINAL .	
Since this application is in condition for allowance except for in accordance with the practice under Ex parte Quayle, 1935	
A shortened statutory period for response to this action is set to is longer, from the mailing date of this communication. Failure application to become abandoned. (35 U.S.C. § 133). Extension 37 CFR 1.136(a).	to respond within the period for response will cause the
Disposition of Claims	
X Claim(s) 1-20	is/are pending in the application.
Of the above, claim(s) 8-11	is/are withdrawn from consideration.
Claim(s)	is/are allowed.
	is/are rejected.
☐ Claim(s)	is/are objected to.
☐ Claims	
Application Papers	
☐ See the attached Notice of Draftsperson's Patent Drawing	Review, PTO-948.
☐ The drawing(s) filed on is/are object	ed to by the Examiner.
☐ The proposed drawing correction, filed on	is □approved □disapproved.
☐ The specification is objected to by the Examiner.	
$\hfill\Box$ The oath or declaration is objected to by the Examiner.	
Priority under 35 U.S.C. § 119	
Acknowledgement is made of a claim for foreign priority to	under 35 U.S.C. § 119(a)-(d).
☐ All ☐ Some* ☐ None of the CERTIFIED copies of	the priority documents have been
☐ received.	
☐ received in Application No. (Series Code/Serial Num	nber)
\square received in this national stage application from the	International Bureau (PCT Rule 17.2(a)).
*Certified copies not received:	
☐ Acknowledgement is made of a claim for domestic priority	y under 35 U.S.C. § 119(e).
Attachment(s)	
☑ Notice of References Cited, PTO-892	
☐ Information Disclosure Statement(s), PTO-1449, Paper No	o(s)
☐ Interview Summary, PTO-413	
☐ Notice of Draftsperson's Patent Drawing Review, PTO-94	8
☐ Notice of Informal Patent Application, PTO-152	
SEE OFFICE ACTION ON TI	HE FOLLOWING PAGES

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DETAILED ACTION

Claim Rejections - 35 U.S.C. § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless --

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1-7 and 12-20 are rejected under 35 U.S.C. 102(b) as being anticipated by WO 96/39632 (Martin et al.).

With regards to claims 1-7, Martin et al. discloses a package for sealing an integrated circuit die comprising, as illustrated in Figures 2 and 4, a first chip of semiconductor material 10; a sensing element 24 formed on the chip; a hollow structure 36 enclosing the sensing element; a metal wall 30 disposed on the chip; and a closure plate 32 made of metal or polymeric material is fixed to the metal wall; a processing circuit for processing electrical signals formed on a second semiconductor chip and in electrical connection with the sensitive element by ballbonds 16 and wirebonds 18. Furthermore, a plastic container encapsulating the chip, sensing element and hollow structure. (See, pages 4-9).

With regards to claims 12-20, the claims are commensurate in scope with claims 1-7 and are rejected for the same reasons as set forth above.

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3. Claims 1-7 and 12-20 are rejected under 35 U.S.C. 102(b) as being anticipated by U.S. Patent 5,438,859 (Yamashita et al.).

With regards to claims 1-7, Yamashita et al. discloses an acceleration sensor comprising, as illustrated in Figures 17-21, a chip of semiconductor material 82 (i.e. a hybrid integrated chip); a sensing element 81 formed on a surface of the chip; a hollow structure (the interior space formed by cover body 87 formed over the semiconductor chip) enclosing the sensing element; a processing circuit 84 and other various circuities are formed in a second semiconductor chip to receive signals in response to the sensor element by conductive pads (i.e. electrodes) 54a-54f as observed in Figures 12-13. (See, column 15, line 45 to column 16, line 17; column 16, lines 55-59).

With regards to claims 12-20, these claims are commensurate in scope with claims 1-7 and are rejected for the same reasons as set forth above.

Response to Amendment

4. Applicant's arguments with respect to claims 1-7 and 12-20 have been considered but are most in view of the new ground(s) of rejection.

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Conclusion

5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Helen Kwok whose telephone number is (703) 308-8149.

Helen C. Kwok Art Unit 2856

hck

July 17, 2000